

Filename: PMP7361_RevA_bom.xls						
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PMP7361 REVA BOM						
COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C29	33pF	Capacitor, Ceramic, 50V, C0G, 5%	603	STD	Std
1	C34	330pF	Capacitor, Ceramic, 50V, C0G, 5%	603	STD	Std
1	C28	470pF	Capacitor, Ceramic, 50V, X7R, 10%	603	STD	TDK
2	C27, C32	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	603	STD	Std
2	C30, C31	0.1uF	Capacitor, Ceramic, 25V, X7R, 10%	603	STD	Std
1	C24	0.47uF	Capacitor, Ceramic, 16V, 10%	603	STD	STD
2	C25, C33	1uF	Capacitor, Ceramic, 25V, X7R, 10%	805	STD	Std
1	C14	220pF	Capacitor, Ceramic, 200V, C0G, 5%	1206	STD	Std
2	C13, C20	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	1206	STD	Std
8	C10, C11, C12, C15, C16, C19, C21, C22	2.2uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	C3225X7R2A225K	TDK
2	C7, C23	2200pF	Capacitor, Ceramic, 2KV, X7R, 10%	1812	1812GC222KAT	AVX
1	C26	22uF	Capacitor, Aluminum, 25V, 20%	5x5.8mm	EEEFK1E220R	Panasonic
4	C8, C9, C17, C18	47uF	Capacitor, Aluminum, 63V, 20%	8x10.2mm	EEVFK1J470P	Panasonic
4	C1, C2, C3, C4	680uF	Capacitor, Aluminum, 63V, 20%	0.630 inch	63ZL680MEFC18x20	Rubycon
0	C5, C6	DNP	Capacitor, Aluminum, 63V, 20%	0.630 inch	63ZL680MEFC18x20	Rubycon
2	D1, D2		Diode, Rectifier, Ultrafast, 2A, 200V	SMB	MURS220	On Semi
1	D3		Diode, Rectifier Ultrafast, 3A, 200V	DPAK	MURD320T4G	On Semi
5	D4, D5, D7, D8, D9		Diode, Switching, 200mA, 75V, 225-mW	SOT-23	BAS16LT1	On Semi
1	D6		Diode, Zener, 39V, 1W	SMA	SMAZ39	Diodes
2	J1, J2		Terminal Block, 2 pin, 6A, 3.5mm	0.27x0.25	ED555/2DS	OST
1	L1	10uH	Inductor, SMT, 4.79A, 22.7 milliohm	10.5x10.5mm	MSS1048-103ML	Coilcraft
1	L2	3.3uH	Inductor, SMT, 1.9A, 80 milliohm	4x4mm	LPS4018-332ML	Coilcraft
1	Q1		MOSFET, NChan, 150V, 35A, 18 milliohm	POWER 56	FDMS86200	Fairchild
2	Q2, Q3		Trans, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906LT1G	On Semi
2	R8, R21	0	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R7	4.7	Resistor, Chip, 1/16W, 1%	603	STD	Std
2	R18, R22	1K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R20	2.43K	Resistor, Chip, 1/16W, 1%	603	STD	Std
2	R12, R17	2.49K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R16	3.01K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R11	4.22K	Resistor, Chip, 1/16W, 1%	603	STD	Std
2	R13, R14	10K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R10	14K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R19	49.9K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R23	3.9	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R9	20	Resistor, Chip, 1/10W, 1%	805	Std	Std

1	R15	49.9K	Resistor, Chip, 1/10W, 1%	805	Std	Std
1	R4	1	Resistor, Chip, 1/4W, 5%	1206	Std	Std
1	R6	12K	Resistor, Chip, 1/4W, 5%	1206	Std	Std
1	R3	51K	Resistor, Chip, 1/2W, 5%	2010	Std	Std
1	R5	51	Resistor, Chip, 1W, 5%	2512	STD	STD
1	R1	470	Resistor, Chip, 1W, 5%	2512	STD	STD
0	R2	DNP	Resistor, Chip, 1W, 5%	2512	STD	STD
1	T1		Transformer, Current Sense, 6A, 100Khz, 30:1	0.330 x 0.360 inch	P8203T	Pulse
1	T2		Transformer, Flyback	1.053 x 1.285 inch	GA3136-BL	Coilcraft
1	U2		IC, Photocoupler, 80-160% CTR	MF4	TCMT1107	Vishay
1	U3		IC, Precision Adjustable Shunt Regulator	SOT23-5	TL431AIDBVR	TI
1	U1		IC, Economy Primary-Side Controller	SO8	UCC2809D-2	TI

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